

HV9910B

Universal High-Brightness LED Driver

Features

- · Switch mode controller for single switch LED drivers
- · Enhanced drop-in replacement to the HV9910
- · Open loop peak current controller
- Internal 8.0 to 450V linear regulator
- · Constant frequency or constant off-time operation
- · Linear and PWM dimming capability
- · Requires few external components for operation

Applications

- DC/DC or AC/DC LED driver applications
- · RGB backlighting LED driver
- Back lighting of flat panel displays
- · General purpose constant current source
- · Signage and decorative LED lighting
- · Chargers

Description

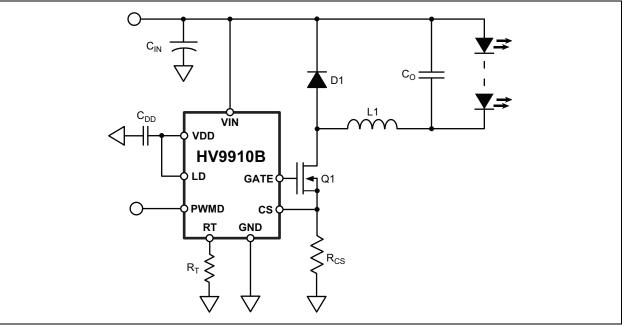
HV9910B is an open loop, current mode control, LED driver IC. This IC can be programmed to operate in either a constant frequency or constant off-time mode. It includes an 8.0 - 450V linear regulator which allows it to work from a wide range of input voltages without the need for an external low voltage supply. HV9910B includes a PWM-dimming input that can accept an external control signal with a duty ratio of 0 - 100% and a frequency of up to a few kilohertz. It also includes a 0 - 250mV linear dimming input which can be used for linear dimming of the LED current.

HV9910B is ideally suited for buck LED drivers. Since the HV9910B operates in open loop current mode control, the controller achieves good output current regulation without the need for any loop compensation. PWM dimming response is limited only by the rate of rise and fall of the inductor current, enabling very fast rise and fall times. HV9910B requires only three external components, apart from the power stage, to produce a controlled LED current. This makes HV9910B an ideal solution for low cost LED drivers.

HV9910B

Package Type **VIN** 1 16 NC 15 NC **NC** 2 14 RT NC 3 CS 4 13 LD **VIN** 1 12 VDD 8 RT GND 5 **CS** 2 7 LD NC 6 11 NC GND 3 6 VDD 10 NC NC 7 GATE 4 5 PWMD GATE 8 9 PWMD 8-Lead SOIC 16-Lead SOIC See Table 2-1 for pin information

Typical Application Circuit



1.0 ELECTRICAL CHARACTERISTICS

ABSOLUTE MAXIMUM RATINGS

V _{IN} to GND	0.5V to +470V
V _{DD} to GND	12V
CS, LD, PWMD, GATE, RT to GND(0.3V to (V _{DD} + 0.3V)
Operating temperature	40°C to +125°C
Storage temperature	65°C to +150°C
Continuous power dissipation ($T_A = +25^{\circ}C$	C)
8-lead SOIC	630 mW
16-lead SOIC	1300 mW

Note: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions, above those indicated in the operational listings of this specification, is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

1.1 ELECTRICAL SPECIFICATIONS

TABLE 1-1: ELECTRICAL CHARACTERISTICS (SHEET 1 OF 2)¹

Symbol	Parameter		Min	Тур	Max	Units	Conditions
Input				•	•	•	·
V _{INDC}	Input DC supply voltage range ²	3	8.0	-	450	V	DC input voltage
I _{INSD}	Shut-down mode supply current	3	-	0.5	1.0	mA	Pin PWMD to GND
Internal Reg	gulator						
V _{DD}	Internally regulated voltage	-	7.25	7.5	7.75	V	V_{IN} = 8.0V, $I_{DD(ext)}$ = 0, 500pF at GATE; R_T = 226k Ω , PWMD = V_{DD}
$\Delta V_{DD, \text{ line}}$	Line regulation of V_{DD}	-	0	-	1.0	V	$\label{eq:VIN} \begin{array}{l} VIN = 8.0 - 450V, \ I_{DD(ext)} = 0, \\ 500pF \ at \ GATE; \ RT = 226k\Omega, \\ PWMD = V_{DD} \end{array}$
$\Delta V_{DD, load}$	Load regulation of V _{DD}	-	0	-	100	mV	$I_{DD(ext)} = 0 - 1.0mA$, 500pF at GATE; R _T = 226k Ω , PWMD = V _{DD}
UVLO	V _{DD} undervoltage lockout threshold	3	6.45	6.7	6.95	V	V _{DD} rising
∆UVLO	V _{DD} undervoltage lockout hysteresis	-	-	500	-	mV	V _{DD} falling
I _{IN,MAX}	Current that the regulator can supply before IC goes into UVLO	4	5.0	-	-	mA	V _{IN} = 8.0V
PWM Dimm	ing						
V _{EN(lo)}	Pin PWMD input low voltage	3	-	-	0.8	V	V _{IN} = 8.0 - 450V
V _{EN(hi)}	Pin PWMD input high voltage	3	2.0	-	-	V	V _{IN} = 8.0 - 450V
R _{EN}	Pin PWMD pull-down resis- tance at PWMD	-	50	100	150	kΩ	V _{PWMD} = 5.0V

Symbol	Parameter	Note	Min	Тур	Мах	Units	Conditions			
Current Sense Comparator										
V	Current sense pull-in thresh-		225	250	275	mV	-40°C < T _A < +85°C			
V _{CS,TH}	old voltage	-	213	250	287	niv	T _A < +125°C			
V _{OFFSET}	Offset voltage for LD com- parator	3	-12	-	12	mV				
T	Current sense blanking	-	150	215	280	ns	$0 < T_A < +85^{\circ}C, V_{LD} = V_{DD},$ $V_{CS} = V_{CS,TH} + 50mV after$ T_{BLANK}			
T _{BLANK}	interval	-	145	215	315	115	-40 < T_A < +125°C, V_{LD} = V_{DD} , V_{CS} = $V_{CS,TH}$ + 50mV after T_{BLANK}			
t _{DELAY}	Delay to output	-	-	80	150	ns	$V_{LD} = V_{DD}, V_{CS} = V_{CS,TH} +$ 50mV after T _{BLANK}			
Oscillator										
¢	Oppillator fraguanay	-	20	25	30	kHz	R _T = 1.00MΩ			
f _{OSC}	Oscillator frequency	-	80	100	120	KITZ	R _T = 226kΩ			
Gate Driver										
ISOURCE	GATE sourcing current	-	165	-	-	mA	V _{GATE} = 0V, V _{DD} = 7.5V			
I _{SINK}	GATE sinking current	-	165	-	-	mA	V_{GATE} = V_{DD} , V_{DD} = 7.5V			
t _{RISE}	GATE output rise time	-	-	30	50	ns	C _{GATE} = 500pF, V _{DD} = 7.5V			
t _{FALL}	GATE output fall time	-	-	30	50	ns	C _{GATE} = 500pF, V _{DD} = 7.5V			

TABLE 1-1: ELECTRICAL CHARACTERISTICS (CONTINUED) (SHEET 2 OF 2)¹

1 Specifications are T_A = 25°C, V_{IN} = 15V unless otherwise noted.

2 Also limited by package-power dissipation limit; Whichever is lower.

3 Applies over the full operating ambient temperature range of $-40^{\circ}C < T_A < +125^{\circ}C$.

4 For design guidance only

TABLE 1-2: THERMAL RESISTANCE

Package	θја
8-Lead SOIC	101°C/W
16-Lead SOIC	83°C/W

2.0 PIN DESCRIPTION

The locations of the pins are listed in Package Type.

TABLE 2-1: PIN DESCRIPTION

Pin #		Function	Description						
8-Lead SOIC	16-Lead SOIC	Function	Description						
1	1	VIN	Input of an 8.0 - 450V linear regulator.						
2	4	CS	Current sense pin used to sense the FET current by means of an external sense resistor. When this pin exceeds the lower of either the internal 250mV or the voltage at the LD pin, the GATE output goes low.						
3	5	GND	Ground return for all internal circuitry. This pin must be electrically connected to the ground of the power train.						
4	8	GATE	Output GATE driver for an external N-channel power MOSFET.						
5	9	PWMD	PWM dimming input of the IC. When this pin is pulled to GND, the GATE driver is turned off. When the pin is pulled high, the GATE driver operates normally.						
6	12	VDD	Power supply for all internal circuits. It must be bypassed with a low ESR capacitor to GND ($\geq 0.1 \mu$ F).						
7	13	LD	Linear dimming input and sets the current sense threshold as long as the voltage at the pin is less than 250mV (typ).						
8	14	RT	Sets the oscillator frequency. When a resistor is connected between RT and GND, the HV9910B operates in constant fre- quency mode. When the resistor is connected between RT and GATE, the IC operates in constant off-time mode.						
-	2, 3, 6, 7, 10, 11, 15, 16	NC	No connection						

3.0 APPLICATION INFORMATION

HV9910B is optimized to drive buck LED drivers using open-loop, peak current mode control. This method of control enables fairly accurate LED current control without the need for high side current sensing or the design of any closed loop controllers. The IC uses very few external components and enables both Linear and PWM-dimming of the LED current.

A resistor connected to the RT pin programs the frequency of operation (or the off-time). The oscillator produces pulses at regular intervals. These pulses set the SR flip-flop in the HV9910B which causes the GATE driver to turn on. The same pulses also start the blanking timer, which inhibits the reset input of the SR flipflop and prevent false turn-offs due to the turn-on spike. When the FET turns on, the current through the inductor starts ramping up. This current flows through the external sense resistor R_{CS} and produces a ramp voltage at the CS pin. The comparators are constantly comparing the CS pin voltage to both the voltage at the LD pin and the internal 250mV. Once the blanking timer is complete, the output of these comparators is allowed to reset the flip-flop. When the output of either one of the two comparators goes high, the flip flop is reset and the GATE output goes low. The GATE goes low until the SR flip-flop is set by the oscillator. Assuming a 30% ripple in the inductor, the current sense resistor RCS can be set using:

$$\mathsf{R}_{\mathsf{CS}} = \frac{0.25\mathsf{V}(\mathsf{orV}_{\mathsf{LD}})}{1.15 \cdot \mathsf{I}_{\mathsf{LED}}(\mathsf{A})}$$

Constant frequency peak current mode control has an inherent disadvantage - at duty cycles greater than 0.5, the control scheme goes into subharmonic oscillations. To prevent this, an artificial slope is typically added to the current sense waveform. This slope compensation scheme will affect the accuracy of the LED current in the present form. However, a constant offtime peak current control scheme does not have this problem and can easily operate at duty cycles greater then 0.5. This control scheme also gives inherent input voltage rejection, making the LED current almost insensitive to input voltage variations. However, this scheme leads to variable frequency operation and the frequency range depends greatly on the input and output voltage variation. HV9910B makes it easy to switch between the two modes of operation by changing one connection (see Section 3.3 "Oscillator").

3.1 Input Voltage Regulator

HV9910B can be powered directly from its VIN pin and can work from 8.0 - 450VDC at its VIN pin. When a voltage is applied at the VIN pin, the HV9910B maintains a constant 7.5V at the VDD pin. This voltage is used to power the IC and any external resistor dividers needed

to control the IC. The VDD pin must be bypassed by a low-ESR capacitor to provide a low impedance path for the high frequency current of the output GATE driver.

HV9910B can also be operated by supplying a voltage at the VDD pin greater than the internally regulated voltage. This will turn off the internal linear regulator of the IC and the HV9910B will operate directly off the voltage supplied at the VDD pin. Please note that this external voltage at the VDD pin should not exceed 12V.

Although the VIN pin of the HV9910B is rated up to 450V, the actual maximum voltage that can be applied is limited by the power dissipation in the IC. For example, if an 8-pin SOIC (junction to ambient thermal resistance $R_{\theta,j-a} = 128^{\circ}$ C/W) HV9910B draws about $I_{IN} = 2.0$ mA from the VIN pin, and has a maximum allowable temperature rise of the junction temperature limited to about $\Delta T = 100^{\circ}$ C, the maximum voltage at the VIN pin would be:

$$V_{IN(MAX)} = \frac{\Delta T}{R_{\Theta j-a}} \cdot \frac{1}{I_{IN}} = \frac{100^{\circ}C}{128^{\circ}C/W} \cdot \frac{1}{2mA} = 390V$$

In these cases, to operate the HV9910B from higher input voltages, a Zener diode can be added in series with the VIN pin to divert some of the power loss from the HV9910B to the Zener diode. In the above example, using a 100V Zener diode will allow the circuit to easily work up to 450V.

The input current drawn from the VIN pin is a sum of the 1.0mA current drawn by the internal circuit and the current drawn by the GATE driver. The GATE driver depends on the switching frequency and the GATE charge of the external FET).

$$I_{IN} \approx 1.0 \text{mA} + Q_{g} \cdot f_{s}$$

In the above equation, f_S is the switching frequency and QG is the GATE charge of the external FET (which can be obtained from the data sheet of the FET).

3.2 Current Sense

The current sense input of the HV9910B goes to the non-inverting inputs of two comparators. The inverting terminal of one comparator is tied to an internal 250mV reference, whereas the inverting terminal of the other comparator is connected to the LD pin. The outputs of both these comparators are fed into an OR GATE and the output of the OR GATE is fed into the reset pin of the flip-flop. Thus, the comparator which has the lowest voltage at the inverting terminal determines when the GATE output is turned off. The outputs of the comparators also include a 150-280ns blanking time which prevents spurious turn-offs of the external FET due to the turn-on spike normally present in peak current mode control. In rare cases, this internal blanking might not be enough to filter out the turn-on spike. In these cases, an external RC filter needs to be added between the external sense resistor (RCS) and the CS pin.

Please note that the comparators are fast with a typical 80ns response time. Hence these comparators are more susceptible to be triggered by noise than the comparators of the HV9910. A proper layout minimizing external inductances will prevent false triggering of these comparators.

3.3 Oscillator

The oscillator in the HV9910B is controlled by a single resistor connected at the RT pin. The equation governing the oscillator time period t_{OSC} is given by:

$$t_{OSC}(\mu s) = \frac{R_{T}(k\Omega) + 22}{25}$$

If the resistor is connected between RT and GND, HV9910B operates in a constant frequency mode and the above equation determines the time-period. If the resistor is connected between RT and GATE, the HV9910B operates in a constant off-time mode and the above equation determines the off-time.

3.4 Gate Output

The GATE output of the HV9910B is used to drive an external FET. It is recommended that the GATE charge of the external FET be less than 25nC for switching frequencies ≤100kHz and less than 15nC for switching frequencies > 100kHz.

3.5 Linear Dimming

The Linear Dimming pin is used to control the LED current. There are two cases when it may be necessary to use the Linear Dimming pin.

- 1. In some cases, when using the internal 250mV, it may not be possible to find the exact RCS value required to obtain the LED current. In these cases, an external voltage divider from the VDD pin can be connected to the LD pin to obtain a voltage (less than 250mV) corresponding to the desired voltage across R_{CS} .
- Linear dimming may be desired to adjust the current level to reduce the intensity of the LEDs. In these cases, an external 0-250mV voltage can be connected to the LD pin to adjust the LED current during operation.

To use the internal 250mV, the LD pin can be connected to VDD.

Note: Although the LD pin can be pulled to GND, the output current will not go to zero. This is due to the presence of a minimum ontime, which is equal to the sum of the blanking time and the delay to output time, or about 450ns. This minimum on-time causes the FET to be on for a minimum of 450ns, and thus the LED current when LD = GND is not zero. This current is also dependent on the input voltage, inductance value, forward voltage of the LEDs, and circuit parasitics. To get zero LED current, the PWMD pin has to be used.

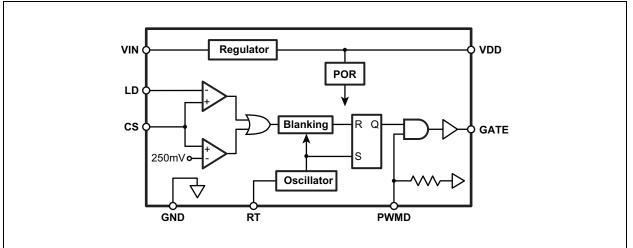
3.6 **PWM** Dimming

PWM Dimming can be achieved by driving the PWMD pin with a low frequency square wave signal. When the PWM signal is zero, the GATE driver is turned off; when the PWMD signal if high, the GATE driver is enabled. The PWMD signal does not turn off the other parts of the IC, therefore, the response of the HV9910B to the PWMD signal is almost instantaneous. The rate of rise and fall of the LED current is thus determined solely by the rise and fall times of the inductor current.

To disable PWM dimming and enable the HV9910B permanently, connect the PWMD pin to VDD.

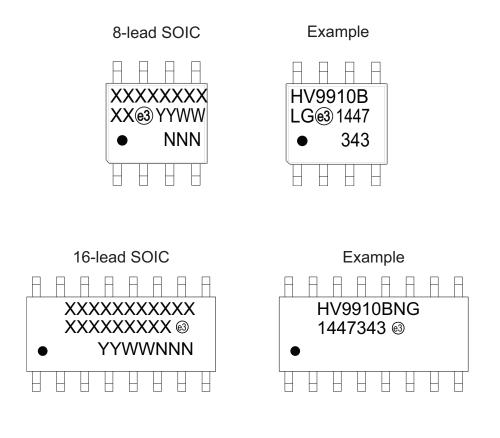
HV9910B

FIGURE 3-1: INTERNAL BLOCK DIAGRAM



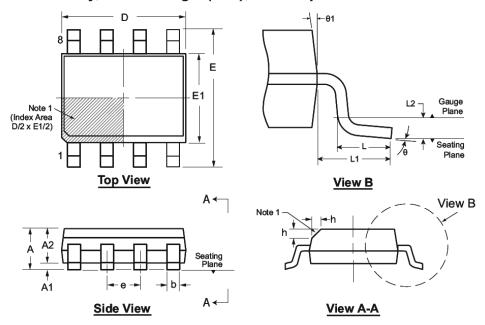
4.0 PACKAGING INFORMATION

4.1 Package Marking Information



Legend	: XXX Y YY WW NNN @3 *	Product Code or Customer-specific information Year code (last digit of calendar year) Year code (last 2 digits of calendar year) Week code (week of January 1 is week '01') Alphanumeric traceability code Pb-free JEDEC [®] designator for Matte Tin (Sn) This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.
	be carrie characters	nt the full Microchip part number cannot be marked on one line, it will d over to the next line, thus limiting the number of available s for product code or customer-specific information. Package may or e the corporate logo.

8-Lead SOIC (Narrow Body) Package Outline (LG/TG) 4.90x3.90mm body, 1.75mm height (max), 1.27mm pitch



Note: For the most current package drawings, see the Microchip Packaging Specification at www.microchip.com/packaging.

Note:

This chamfer feature is optional. A Pin 1 identifier must be located in the index area indicated. The Pin 1 identifier can be: a molded mark/identifier; an embedded metal marker; or a printed indicator. 1.

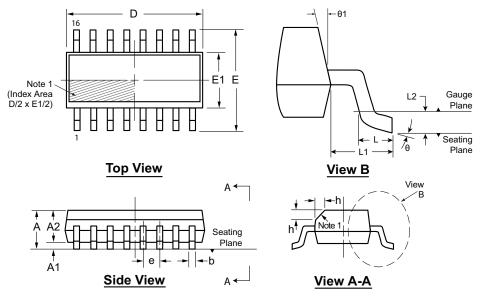
Symbo	I	A	A1	A2	b	D	E	E1	e	h	L	L1	L2	θ	θ1
	MIN	1.35*	0.10	1.25	0.31	4.80*	5.80*	3.80*		0.25	0.40			0 0	5 ⁰
Dimension (mm)	NOM	-	-	-	-	4.90	6.00	3.90	1.27 BSC	-	-	1.04 REF	0.25 BSC	-	-
()	MAX	1.75	0.25	1.65*	0.51	5.00*	6.20*	4.00*	200	0.50	1.27		200	8 0	15 ⁰

JEDEC Registration MS-012, Variation AA, Issue E, Sept. 2005. * This dimension is not specified in the JEDEC drawing.

Drawings are not to scale.

16-Lead SOIC (Narrow Body) Package Outline (NG)

9.90x3.90mm body, 1.75mm height (max), 1.27mm pitch



Note: For the most current package drawings, see the Microchip Packaging Specification at www.microchip.com/packaging.

Note:

 This chamfer feature is optional. If it is not present, then a Pin 1 identifier must be located in the index area indicated. The Pin 1 identifier can be: a molded mark/identifier; an embedded metal marker; or a printed indicator.

Symbo	bl	Α	A1	A2	b	D	Е	E1	е	h	L	L1	L2	θ	θ1
	MIN	1.35*	0.10	1.25	0.31	9.80*	5.80*	3.80*		0.25	0.40			0 0	5°
Dimension (mm)	NOM	-	-	-	-	9.90	6.00	3.90	1.27 BSC	-	-		0.25 BSC	-	-
()	MAX	1.75	0.25	1.65*	0.51	10.00*	6.20*	4.00*		0.50	1.27		200	8 0	15 ⁰

JEDEC Registration MS-012, Variation AC, Issue E, Sept. 2005. * This dimension is not specified in the JEDEC drawing.

Drawings are not to scale.

APPENDIX A: REVISION HISTORY

Revision A (January 2015)

Update file to new format

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	<u>xx</u> - x - x		Exar	nples:	
Device	Package Environmental Media Options Type	á	a)	HV9910BLG-G:	8-lead SOIC package, 3300/reel.
		I	b)	HV9910BNG-G	16-lead SOIC package, 45/tube
Device:	HV9910B= Universal High-Brightness LED Driver	(c)	HV9910BNG-G-M901:	16-lead SOIC package, 2600/reel.
Package:	LG = 8-lead SOIC	(d)	HV9910BNG-G-M934:	16-lead SOIC package, 2600/reel.
T donago.	NG = 16-lead SOIC				
Environmental	G = Lead (Pb)-free/ROHS-compliant package				
Media Type:	(blank) = 3300/reel for LG package, 45/Tube for NG package				
	M901 = 2600/reel for NG package				
	M934 = 2600/reel for NG package				
	dia Types M901 and M934, the base quantity for tape and reel was stan- d to 2600/reel. Both options will result in delivery of the same number of el.				

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